

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









Discontinued Product

This device is no longer in production. The device should not be purchased for new design applications. Samples are no longer available.

Date of status change: November 1, 2010

Recommended Substitutions:

For existing customer transition, and for new customers or new applications, refer to the $\underline{A1125}$.

NOTE: For detailed information on purchasing options, contact your local Allegro field applications engineer or sales representative.

Allegro MicroSystems, Inc. reserves the right to make, from time to time, revisions to the anticipated product life cycle plan for a product to accommodate changes in production capabilities, alternative product availabilities, or market demand. The information included herein is believed to be accurate and reliable. However, Allegro MicroSystems, Inc. assumes no responsibility for its use; nor for any infringements of patents or other rights of third parties which may result from its use.



The A3340 Hall effect switch is an extremely temperature-stable

and stress-resistant sensor IC especially suited for operation over extended temperature ranges up to 150°C. Superior

high-temperature performance is made possible through

dynamic offset cancellation, which reduces the residual offset

voltage normally caused by device overmolding, temperature

The device includes on a single silicon chip a voltage regulator, Hall-voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, and a short-circuit protected open-collector output to sink up to 25 mA. A south pole of sufficient strength will turn the output off. An on-board regulator permits operation with supply voltages of 4.2 to 24 volts. Two package styles provide a magnetically optimized package

Description

dependencies, and thermal stress.

Features and Benefits

- Resistant to physical stress
- Superior temperature stability
- Output short-circuit protection
- Operation from unregulated supply
- Reverse battery protection
- Solid-state reliability
- Small size

and 3 pin SIP (suffix UA)



Packages: 3 pin SOT23W (suffix LH),

through hole mounting. The A3340 complements the A3240, which offers the same

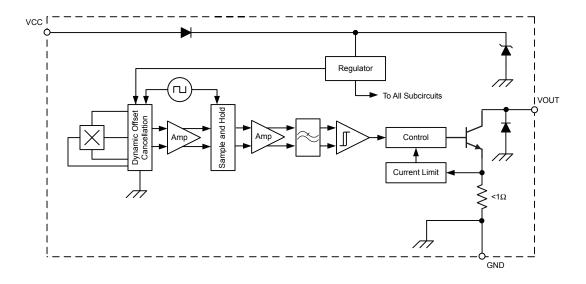
features, but with the opposite output polarity.

for most applications. Suffix LH is an SOT23W surface mount

package and while suffix UA is a three-lead ultramini SIP for

Not to scale

Functional Block Diagram



Selection Guide

Part Number	Packing ¹	Mounting	Ambient, T _A	B _{RP} (Min)	B _{OP} (Max)
A3340EUA-T ²	Bulk, 500 pieces/bag	3-pin SIP through hole	-40°C to 85°C	E	50
A3340LUA-T ²	Bulk, 500 pieces/bag	3-pin SIP through hole	-40°C to 150°C	5	

¹Contact Allegro for additional packing options.

²Variant is in production but has been determined to be LAST TIME BUY. This classification indicates that the variant is obsolete and notice has been given. Sale of the variant is currently restricted to existing customer applications. The variant should not be purchased for new design applications because of obsolescence in the near future. Samples are no longer available. Status date change May 3, 2010. Deadline for receipt of LAST TIME BUY orders is October 29, 2010.



Absolute Maximum Ratings

Characteristic	Symbol	Notes	Rating	Units
Supply Voltage	V _{CC}		26.5	V
Reverse Supply Voltage	V _{RCC}		-30	V
Output Off Voltage	V _{OUT}		26	V
Reverse Output Voltage	V _{ROUT}		-0.5	V
Continuous Output Current	Іоит	Internal current limiting (intended to protect the device from output short circuits)	25	mA
Reverse Output Current	I _{ROUT}		-50	mA
Magnetic Flux Density	В		Unlimited	G
Operating Ambient Temperature	T _A	Range E	-40 to 85	°C
Operating Ambient Temperature		Range L	-40 to 150	°C
Maximum Junction Temperature	T _J (max)		165	°C
Storage Temperature	T _{stg}		-65 to 170	°C



A3340

Chopper-Stabilized, Precision Hall-Effect Switch

Operating Characteristics, valid over T_A, unless otherwise noted

Characteristic	Symbol	Test Conditions	Min.	Typ. ¹	Max.	Units
Electrical Characteristics						
Supply Voltage Range ²	V _{CC}	Operating, T _J < 165°C	4.2	_	24	V
Output Leakage Current	I _{OFF}	V _{OUT} = 24 V, B > B _{OP}	_	_	10	μA
Output Saturation Voltage	V _{OUT(SAT)}	I _{OUT} = 20 mA, B < B _{RP}	_	270	500	mV
Output Current Limit	I _{OM}	B < B _{RP}	30	_	60	mA
Power-On Time	t _{PO}	V _{CC} > 4.2 V	_	_	50	μs
Chopping Frequency	f _C		_	340	_	kHz
Output Rise Time	t _r	R_{LOAD} = 820 Ω , C_{LOAD} = 20 pF	_	0.2	2.0	μs
Output Fall Time	t _f	R_{LOAD} = 820 Ω , C_{LOAD} = 20 pF	_	0.1	2.0	μs
Supply Current	I _{cc}	B < B _{RP} , V _{CC} = 12 V	_	3.0	6.0	mA
		B > B _{OP} , V _{CC} = 12 V	_	4.0	6.0	mA
Reverse Battery Current	I _{RCC}	V _{RCC} = -30 V	_	_	-5.0	mA
Zener Voltage	V_{ZD}	$V_Z + V_D$, $I_{CC} = 15$ mA, $T_A = 25$ °C	28	32	37	V
Zener Impedance	Z _{ZD}	$Z_Z + Z_D$, $I_{CC} = 15$ mA, $T_A = 25$ °C	_	50	_	Ω
Magnetic Characteristics ³						
Operate Point ⁴	B _{OP}		_	35	50	G
Release Point ⁴	B _{RP}		5.0	25	_	G
Hysteresis	B _{hys}	B _{OP} – B _{RP}	_	6	_	G

 $^{^1}$ Typical data are for initial design estimations only, and assume optimum manufacturing and application conditions, such as T_A = 25°C and V_{CC} = 12 V. Performance may vary for individual units, within the specified maximum and minimum limits.



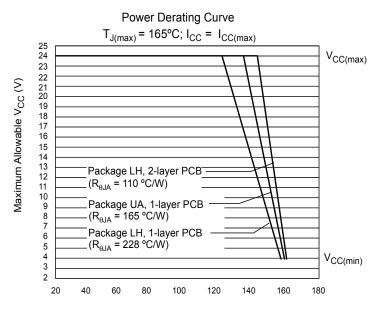
²Maximum voltage must be adjusted for power dissipation and junction temperature.

³1 G (gauss) = 0.1 mT (millitesla).

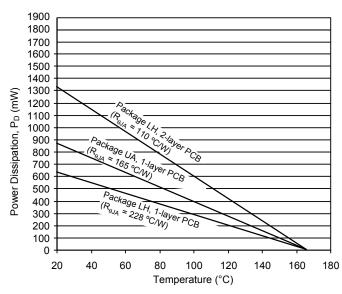
 $^{^{4}}B_{OP}$ = operate point (output turns off); B_{RP} = release point (output turns on).

THERMAL CHARACTERISTICS may require derating at maximum conditions, see application information

Characteristic	Symbol	Test Conditions	Value	Units
Package Thermal Resistance	$R_{ heta JA}$	Package LH, 1-layer PCB with copper limited to solder pads	228	°C/W
		Package LH, 2-layer PCB with 0.463 in? of copper area each side connected by thermal vias	110	°C/W
		Package UA, 1-layer PCB with copper limited to solder pads	165	°C/W

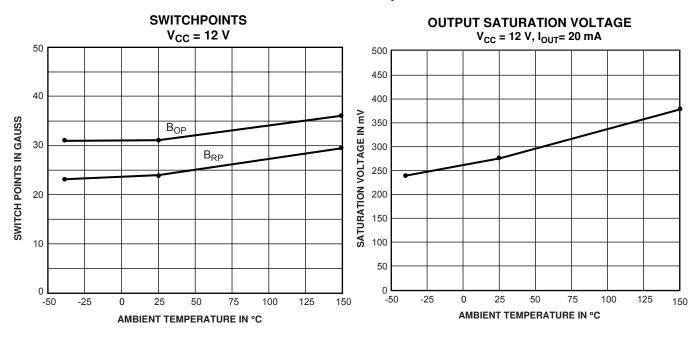


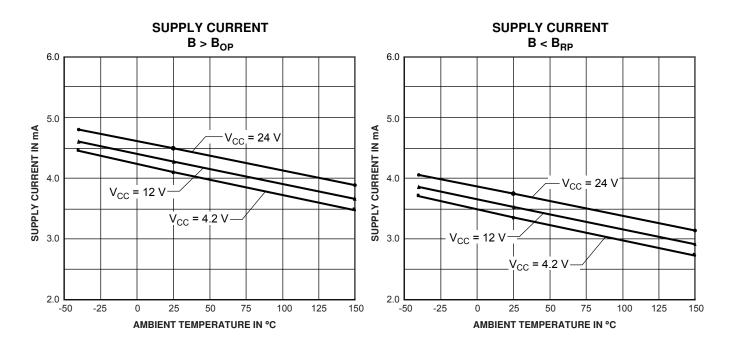
Power Dissipation versus Ambient Temperature





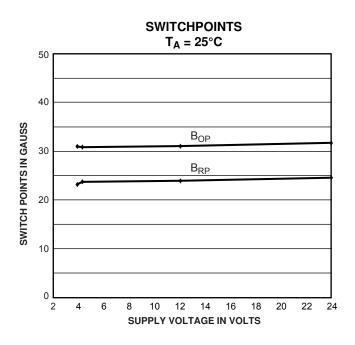
TYPICAL OPERATING CHARACTERISTICS as a function of temperature

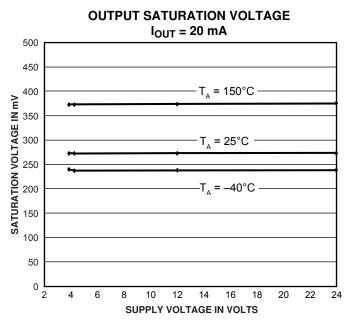


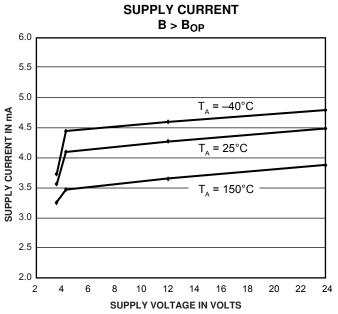




TYPICAL OPERATING CHARACTERISTICS as a function of supply voltage





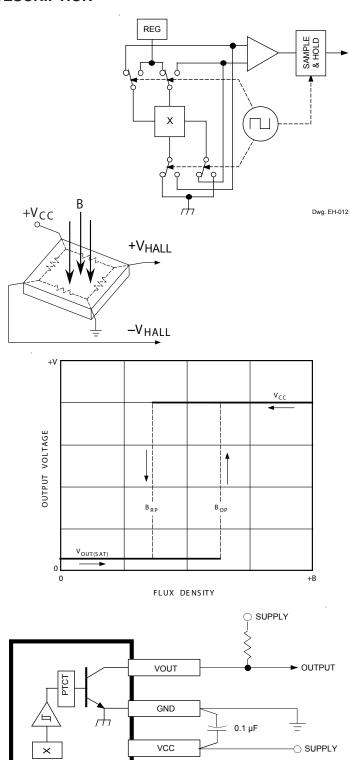


FUNCTIONAL DESCRIPTION

Chopper-Stabilized Technique. The Hall element can be considered as a resistor array similar to a Wheatstone bridge. A large portion of the offset is a result of the mismatching of these resistors. These devices use a proprietary dynamic offset cancellation technique, with an internal high-frequency clock to reduce the residual offset voltage of the Hall element that is normally caused by device overmolding, temperature dependencies, and thermal stress. The chopper-stabilizing technique cancels the mismatching of the resistor circuit by changing the direction of the current flowing through the Hall plate using CMOS switches and Hall voltage measurement taps, while maintaining the Hall-voltage signal that is induced by the external magnetic flux. The signal is then captured by a sample-and hold circuit and further processed using low-offset bipolar circuitry. This technique produces devices that have an extremely stable quiescent Hall output voltage, are immune to thermal stress, and have precise recoverability after temperature cycling. This technique will also slightly degrade the device output repeatability. A relatively high sampling frequency is used in order that faster signals can be processed.

More detailed descriptions of the circuit operation can be found in: Technical Paper STP 97-10, Monolithic Magnetic Hall Sensing Using Dynamic Quadrature Offset Cancellation and Technical Paper STP 99-1, Chopper-Stabilized Amplifiers With A Track-and-Hold Signal Demodulator. Operation. The output of these devices switches high (turns off) when a magnetic field (south pole) perpendicular to the Hall element exceeds the operate point threshold (B_{OP}). When the magnetic field is reduced below the release point (B_{RP}), the device output goes low (turns on). After turn-on, the output is capable of sinking 25 mA and the output voltage is V_{OUT(SAT)}. The difference in the magnetic operate and release points is the hysteresis (B_{hvs}) of the device. This built-in hysteresis allows clean switching of the output even in the presence of external mechanical vibration and electrical noise. Applications. It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall element) between the supply and ground of the device to reduce both external noise and noise generated by the chopper stabilization technique.

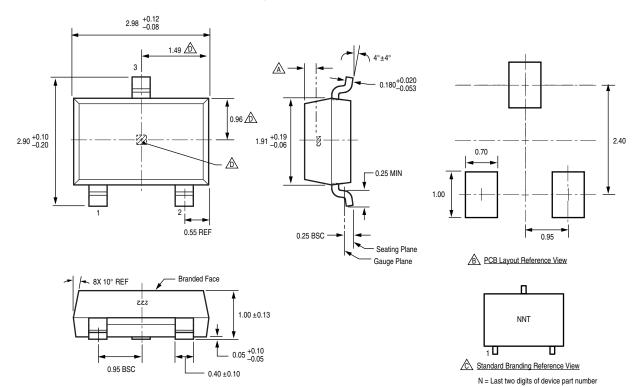
The simplest form of magnet that will operate these devices is a ring magnet. Other methods of operation, such as linear magnets, are possible. Extensive applications information on magnets and Hall-effect devices is also available in Application Note 27701, or at www.allegromicro.com.





Dwg. EH-013

Package LH, 3-Pin (SOT-23W)



For Reference Only; not for tooling use (reference dwg. 802840) Dimensions in millimeters

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions Exact case and lead configuration at supplier discretion within limits shown

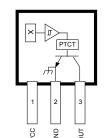
Active Area Depth, 0.28 mm REF

Reference land pattern layout
All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances

Branding scale and appearance at supplier discretion

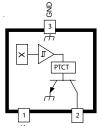
hall element, not to scale

Pin-out Diagrams



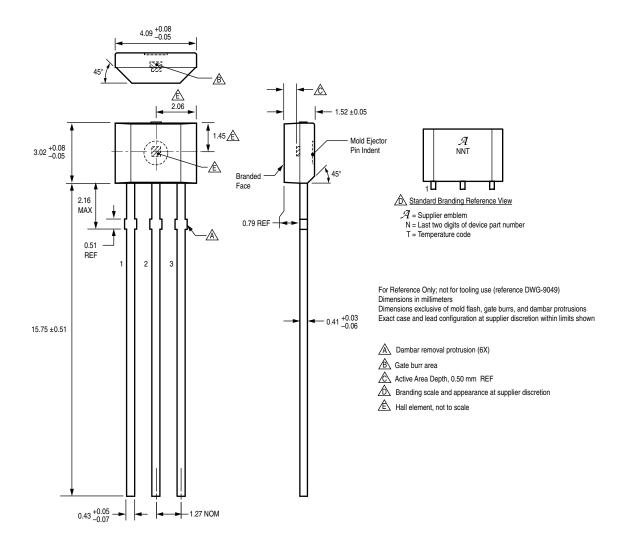
Package UA





Terminal List			>	
Name	Description	Number		
Name	Description	Package LH	Package UA	
VCC	Connects power supply to chip	1	1	
VOUT	Output from circuit	2	3	
GND	Ground	3	2	

Package UA, 3-Pin SIP



Copyright ©2004-2010, Allegro MicroSystems, Inc.

Allegro MicroSystems, Inc. reserves the right to make, from time to time, such departures from the detail specifications as may be required to permit improvements in the performance, reliability, or manufacturability of its products. Before placing an order, the user is cautioned to verify that the information being relied upon is current.

Allegro's products are not to be used in life support devices or systems, if a failure of an Allegro product can reasonably be expected to cause the failure of that life support device or system, or to affect the safety or effectiveness of that device or system.

The information included herein is believed to be accurate and reliable. However, Allegro MicroSystems, Inc. assumes no responsibility for its use; nor for any infringement of patents or other rights of third parties which may result from its use.

For the latest version of this document, visit our website:

www.allegromicro.com

